

<b>L Number</b>	<b>Hits</b>	<b>Search Text</b>	<b>DB</b>	<b>Time stamp</b>
<b>1</b>	<b>5</b>	<b>assembly and pads near copp r and bump near aluminum</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/10/21 16:02</b>
<b>2</b>	<b>5</b>	<b>("4130454"   "5244539"   "5268048"   "5574386"   "6134776").PN.</b>	<b>USPAT</b>	<b>2003/10/21 16:01</b>
<b>3</b>	<b>0</b>	<b>pcb near assembly and pads near copper and bump near aluminum</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/10/21 16:02</b>
<b>4</b>	<b>0</b>	<b>pcb and pads near copper and bump near aluminum</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/10/21 16:02</b>
<b>5</b>	<b>6</b>	<b>pads near copper and bump near aluminum</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/10/21 16:05</b>
<b>6</b>	<b>5</b>	<b>assembly and copper near pads and aluminum near bumps</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/10/21 16:07</b>
<b>7</b>	<b>3</b>	<b>mounting adj pads near copper and bumps</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/10/21 16:08</b>
<b>8</b>	<b>0</b>	<b>mounting adj pads near copper and bumps near aluminum</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/10/21 16:09</b>
<b>9</b>	<b>0</b>	<b>mounting adj pads near copper and bumps same aluminum</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/10/21 16:09</b>
<b>10</b>	<b>0</b>	<b>mounting adj pads near copper and bumps and aluminum</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/10/21 16:09</b>

11	4	mounting adj pads near copper and aluminum	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 16:12
12	0	mounting adj pads near copper and aluminum near bumps	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 16:12
13	6	mounting adj pads and aluminum near bumps	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 16:13
14	4	copper adj pads and aluminum near bumps	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 16:13
15	1	"6139977".PN.	USPAT	2003/10/21 16:15
16	18	("4000842"   "4005472"   "4380042"   "4849856"   "4873123"   "4899207"   "4914551"   "4979663"   "5029386"   "5034591"   "5098008"   "5099393"   "5278724"   "5336564"   "5386341"   "5397921"   "5435732"   "5770480").PN.	USPAT	2003/10/21 16:16
-	2	6381837.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 15:58
-	11	("3801388"   "3953924"   "4404059"   "5177863"   "5453581"   "5489750"   "5542174"   "5738797"   "5932993"   "6115262"   "6169253").PN.	USPAT	2003/10/21 10:27
-	0	"an electronic circuit assembly".ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 10:39
-	0	"an electronic circuit assembly"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 10:40
-	645	"electronic circuit assembly"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 10:40

-	42	"electronic circuit assembly" and 29/\$.ccls.	USPAT; US-PGPUB; EP ; JPO; DERWENT; IBM_TDB	2003/10/21 10:49
-	8	("5132864"   "5357060"   "5386087"   "5425647"   "5453581"   "5486657"   "5644475"   "5707714").PN.	USPAT	2003/10/21 10:44
-	11	("3801388"   "3953924"   "4404059"   "5177863"   "5453581"   "5489750"   "5542174"   "5738797"   "5932993"   "6115262"   "6169253").PN.	USPAT	2003/10/21 10:47
-	270	29/840.ccls. and substrate and pads and chip and bumps	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 11:13
-	4	("3373481"   "5874780"   "5889326"   "6081997").PN.	USPAT	2003/10/21 10:54
-	43	("4157932"   "4554033"   "4612083"   "4640981"   "4680226"   "4749120"   "4818728"   "4868979"   "4917466"   "4967314"   "5074947"   "5084961"   "5086558"   "5136365"   "5147210"   "5196371"   "5237130"   "5296063"   "5298279"   "5318651"   "5329423"   "5341564"   "5363277"   "5384952"   "5477419"   "5543585"   "5545281"   "5611140"   "5637176"   "5667884"   "5674780"   "5686702"   "5714252"   "5747101"   "5840417"   "5843251"   "5861678"   "5863970"   "5879761"   "5918364"   "5925930"   "5975408"   "6027575").PN.	USPAT	2003/10/21 10:58
-	167	29/832.ccls. and substrate and pads and chip and bumps	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 11:36
-	12	("3670409"   "4818728"   "4893172"   "4975079"   "5006792"   "5086337"   "5196726"   "5199879"   "5615824"   "5802699"   "5880590"   "5984691").PN.	USPAT	2003/10/21 11:17

-	40	("2014524"   "2774747"   "3401126"   "3429040"   "3757075"   "3971610"   "4113981"   "4157932"   "4442966"   "4554033"   "4587038"   "4612083"   "4640981"   "4648179"   "4695404"   "4719140"   "4764804"   "4818728"   "4840302"   "4872261"   "4914057"   "4917466"   "4922321"   "4967314"   "4985107"   "4991000"   "5001302"   "5068714"   "5074947"   "5086558"   "5090119"   "5147210"   "5187020"   "5196371"   "5218234"   "5270253"   "5290423"   "5329423"   "5508228"   "5674780").PN.	USPAT	2003/10/21 11:22
-	0	29/832.ccls. and insulation near substrate and mounting adj pads and bumps	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 11:36
-	1	29/832.ccls. and insulation near substrate and mounting adj pads	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 11:37
-	3	29/832.ccls. and insulation same substrate and mounting adj pads	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 11:37
-	80	29/\$.ccls. and insulation same substrate and pads and bumps	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 11:58
-	6	insulation near substrate and mounting near pads and bumps	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 12:00
-	2	("5844304"   "6022757").PN.	USPAT	2003/10/21 11:59
-	16	insulation near substrate and mounting near pads	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 12:01
-	229	ceramic near substrate and mounting near pads	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 12:01

-	1	eramic near substrate and mounting near pads and component near bumps	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 12:04
-	3	("4912545"   "4922322"   "5196726").PN.	USPAT	2003/10/21 12:04
-	6	substrate and mounting near pads and component near bumps	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 12:05
-	57	Jairazbhoy near Vivek .inv.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 12:05
-	12	29/832.ccls. and insulation same substrate and pads and bumps	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 12:38
-	278	pcb and footprint and bumps	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 13:09
-	278	pcb and footprint and bumps	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 13:10
-	262	pcb and footprint and pads and bumps	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 14:51
-	18	("4423468"   "5047711"   "5059557"   "5126286"   "5222014"   "5235496"   "5239191"   "5239198"   "5304843"   "5356838"   "5388029"   "5731222"   "5731630"   "5783464"   "5832600"   "5880011"   "5888884"   "5904496").PN.	USPAT	2003/10/21 13:19
-	1	1999-337361.NRAN.	DERWENT	2003/10/21 14:46
-	4	561547.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 14:52

-	2	5615477.pn.	USPAT; US-PGPUB; EP ; JPO; DERWENT; IBM_TDB USPAT	2003/10/21 14:52
-	48	("3868724"   "3965568"   "4219882"   "4221047"   "4425401"   "4628406"   "4647959"   "4700473"   "4730238"   "4748495"   "4772936"   "4774634"   "4814855"   "4862153"   "4878098"   "4891789"   "4893216"   "4906823"   "4924352"   "4942452"   "4953460"   "4967950"   "4980034"   "5001542"   "5008997"   "5019673"   "5019944"   "5021630"   "5033665"   "5045975"   "5073118"   "5109601"   "5111279"   "5112462"   "5132879"   "5133495"   "5137791"   "5168346"   "5203075"   "5227589"   "5242100"   "5261593"   "5275330"   "5289631"   "5316787"   "5364707"   "5435732"   "5450290").PN.		2003/10/21 14:53